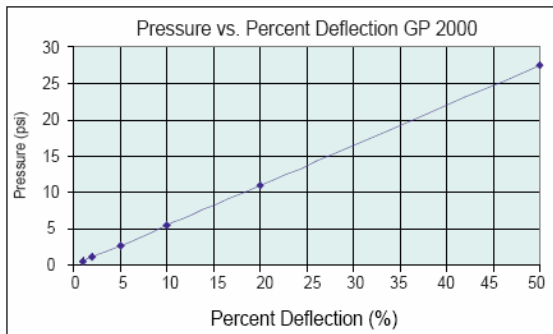


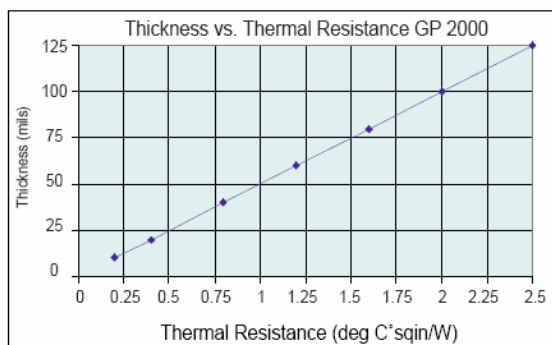
GAP PAD™ 2000

High Performance Thermally Conductive Gap Filling Material

Gap Pad 2000 is a highly conductive filled low modulus polymer that acts as a thermal interface between electrical components and heat sinks. The conformable nature allows the material to fill air gaps to enhance the thermal performance of electrical systems. The tacky nature of both sides of the material allows for good compliance to the adjacent surfaces of components. This high thermally conductive reinforced material is available in thicknesses from 0.010" to 0.125".



To calculate the approximate amount of deflection for a specific material thickness, at a given pressure, refer to the graph above. Multiply the thickness of the material by the percentage at the given pressure.*



The resultant thickness of the Gap Pad will determine the thermal resistance. Subtracting the initial gap pad thickness by the deflection value, obtained above, will give the resultant thickness. Refer to the second graph to obtain the thermal resistance for a given thickness of material.

Typical Applications

- Heat Pipe Assemblies
- RDRAM™ Memory Modules
- CDROM Cooling
- Area where heat needs to be transferred to a frame, chassis, or other type of heat spreader.
- Between a CPU and Heat Spreader

Bergquist Gap Pad 2000

Physical Properties	Typical Value	Test Method	
Color	Grey	Visual	
Thickness of Substrate	0.010" to 0.125"	ASTM D374	
Specific Gravity	2.9	ASTM D792	
Heat Capacity	1.0 J/g-K	ASTM C351	
Continuous Use Temperature	-60°C to 200°C		
Hardness (Shore Type 00)	Thickness	ASTM D2240	
	0.010"		80
	0.125"		50
Young's Modulus* (psi)	Rate 0.01"/min.	Modulus 55 ASTM D575	

Thermal

Thermal Conductivity (@10 psi)	2.0 W/m-K	ASTM D5470
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Electrical

Dielectric Breakdown Voltage	>3 kV	ASTM D149
Dielectric Constant	5	ASTM D150
Volume Resistivity	10 ¹¹ Ohm-meter	ASTM D257
UL Recognized	94V-0 (pending)	U.L.

*Graphs and data generated from Young's Modulus, calculated using 0.01 inch/min. step rate of strain with a sample size of 0.79 inch². For more information on Gap Pad modulus refer to Bergquist Application Note #116.

Gap Pad 2000 is available in die-cut parts and in roll form (converted or unconverted). The material is compatible with dispensing equipment for high volume production.